

Amendments to the Claims:

This listing of the claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

Claims 1-6 (cancelled)

Claim 7 (withdrawn): A wiring method, comprising the steps of:
providing a first semiconductor chip having a connection pad;
positioning a second semiconductor chip on said first semiconductor chip, said second semiconductor chip having a connection pad; and
electrically connecting between said connection pad of said first semiconductor chip and said connection pad of said second semiconductor chip.

Claim 8 (withdrawn): A wiring method in accordance with claim 7, wherein said connection pad of said first semiconductor chip is electrically connected with said connection pad of said second electrode through a bonding wire.

Claim 9 (withdrawn): A wiring method in accordance with claim 8, wherein said connection pad on said first semiconductor chip positions in a region where said first semiconductor faces to said second semiconductor chip, said connection pad on said second semiconductor chip positions in said region, and said connection pad on said first semiconductor chip is electrically connected with said connection pad on said second semiconductor chip through a conductive member positioned in said region.

Claim 10 (currently amended): A semiconductor device, comprising:
a circuit board;

a first semiconductor chip positioned on the circuit board, ~~the first semiconductor chip being sized and configured to be smaller than the circuit board so that the first semiconductor chip on the circuit board is confined within an outer periphery of the circuit board; and~~ ;

a second semiconductor chip positioned on the first semiconductor chip, ~~the second semiconductor chip being sized and configured to be smaller than the first semiconductor chip so that the second semiconductor chip on the first semiconductor chip is confined within an outer periphery of the first semiconductor chip~~; wherein

(a) the circuit board has a first pad, a second pad spaced away from the first pad in a direction along ~~the~~ an outer periphery of the first semiconductor chip, and a wire connecting between the first pad and the second pad on a surface of the circuit board supporting the first semiconductor chip, the wire being printed on the circuit board together with the first and second pads, and the wire extending along the outer periphery of the first semiconductor chip between the first and second pads;

(b) the second semiconductor chip has a third pad positioned adjacent to the second pad but away from the first pad on the circuit board; and

(c) the second pad on the circuit board and the third pad on the second semiconductor chip are electrically connected through a bonding wire, so that the third pad on the second semiconductor chip is electrically connected with the first pad on the circuit board through the bonding wire, the second pad on the circuit board, and the wire on the circuit board.

Claims 11-12 (cancelled)

Claim 13 (new): The semiconductor device according to claim 10, wherein the semiconductor device is mounted on a motherboard.

Claim 14 (new): The semiconductor device according to claim 10, wherein the circuit board further comprises a fourth pad positioned adjacent the outer periphery of the first semiconductor chip.

Claim 15 (new): The semiconductor device according to claim 10, wherein the first semiconductor chip has a fifth pad positioned adjacent the outer periphery of the first semiconductor chip.

Claim 16 (new): The semiconductor device according to claim 10, wherein the second semiconductor chip has a sixth pad positioned adjacent the outer periphery of the second semiconductor chip.

Claim 17 (new): A semiconductor device, comprising:
a circuit board;
a first semiconductor chip positioned on the circuit board;
a second semiconductor chip positioned on the first semiconductor chip; wherein
(a) the circuit board has a first pad, a second pad spaced away from the first pad in a direction along an outer periphery of the first semiconductor chip;
(b) the first semiconductor chip has a third pad, a fourth pad spaced away from the third pad in a direction along an outer periphery of the second semiconductor chip, the third and fourth pads being positioned adjacent to the first and second pads, respectively, and a wire connecting between the third pad and the fourth pad on a surface of the first semiconductor chip supporting the second semiconductor chip, the wire being printed on the first semiconductor chip together with the third and fourth pads, and the

wire extending along the outer periphery of the second semiconductor chip between the third and fourth pads;

- (c) the second semiconductor chip has a fifth pad positioned adjacent to the third pad but away from the fourth pad on the first semiconductor chip; and
- (d) the first pad on the circuit board and the third pad on the first semiconductor chip, the first pad on the circuit board and the fifth pad on the second semiconductor chip, and the second pad on the circuit board and the fourth pad on the first semiconductor chip are electrically connected through respective bonding wires.

Claim 18 (new): The semiconductor device according to claim 17, wherein the semiconductor device is mounted on a motherboard.

Claim 19 (new): A semiconductor device, comprising:

- a circuit board;
- a first semiconductor chip positioned on the circuit board;
- a second semiconductor chip positioned on the first semiconductor chip; wherein
 - (a) the circuit board has a first pad and a second pad spaced away from the first pad in a direction along an outer periphery of the first semiconductor chip;
 - (b) the second semiconductor chip has a third pad positioned adjacent to the second pad but away from the first pad on the circuit board; and
 - (c) the first and second pads on the circuit board and the second pad on the circuit board and the third pad on the second semiconductor chip are electrically connected through respective bonding wires.

Claim 20 (new): The semiconductor device according to claim 19, wherein the first semiconductor chip has a sixth pad positioned adjacent the outer periphery of the first semiconductor chip.

Claim 21 (new): The semiconductor device according to claim 19, wherein the semiconductor device is mounted on a motherboard.